

**WHAT IS CLAIMED IS:**

1. An image sensor comprising:
  - (a) a substrate having a plurality of photosensitive sites for capturing an image and a plurality of additional photosensitive sites adjacent the image capturing photosensitive sites in which there is no image capture; and
  - (b) a digital signal embedded in one or more of the additional photosensitive sites for the purpose of identification.
2. The image sensor as in claim 1, wherein the digital signal identifies individually or in any combination particular manufacturer, lot, wafer, and/or position on the wafer during manufacture of the image sensor
3. The image sensor as in claim 1 wherein the embedded digital signal includes a watermark for electronic identification of the sensor without affecting any aspect of the image captured by the plurality of sites used to capture the image.
4. The image sensor as in claim 1 further comprising an electronic structure for preventing charge from passing to an amplifier for identifying the embedded digital signal.
5. A method for creating an image sensor comprising the steps of:
  - (a) providing a substrate having a plurality of photosensitive sites for capturing an image and a plurality of additional photosensitive sites adjacent the image capturing photosensitive sites in which there is no image capture; and
  - (b) embedding a digital signal in one or more of the additional photosensitive sites for the purpose of identification.
6. The method as in claim 5 wherein step (b) includes etching a protective metal spanning one or more of the additional photosensitive sites in a predefined sequence.

7. The method as in claim 5 where the predefined sequence is repeated in a predetermined manner to provide redundancy as a safeguard for problems which might affect the ability of the photoactive site from registering a signal.

8. The method as in claim 5 wherein the predefined sequence is used as a watermark for electronic identification.

9. The method as in claim 5 further comprising providing an electronic structure for preventing charge from passing to an amplifier for identifying the embedded digital signal.

10. An image capture device comprising:

(a) an image sensor comprising:

(a1) a substrate having a plurality of photosensitive sites for capturing an image and a plurality of additional photosensitive sites adjacent the image capturing photosensitive sites in which there is no image capture; and

(a2) a digital signal embedded in one or more of the additional photosensitive sites for the purpose of identification.

12. The image capture device as in claim 10, wherein the digital signal identifies individually or in any combination particular manufacturer, lot, wafer, and/or position on the wafer during manufacture of the image sensor

13. The image capture device as in claim 10, wherein the embedded digital signal includes a watermark for electronic identification of the sensor without affecting any aspect of the image captured by the plurality of sites used to capture the image.

14. The image capture device as in claim 10 further comprising an electronic structure for preventing charge from passing to an amplifier for identifying the embedded digital signal.